



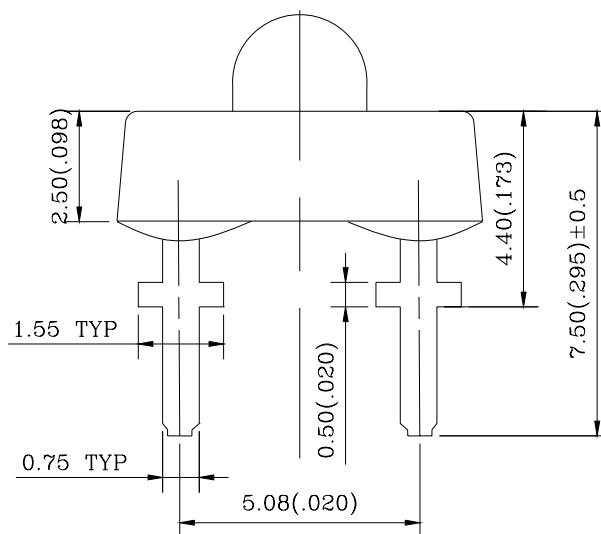
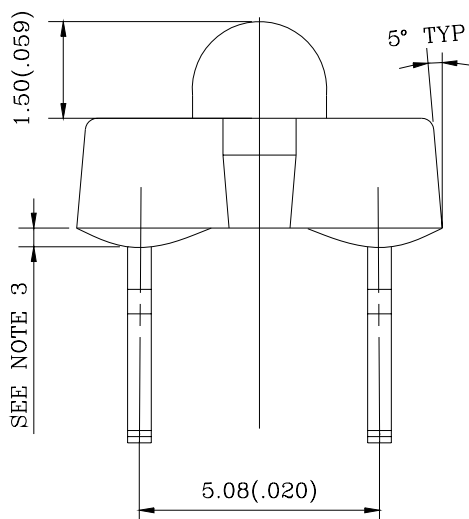
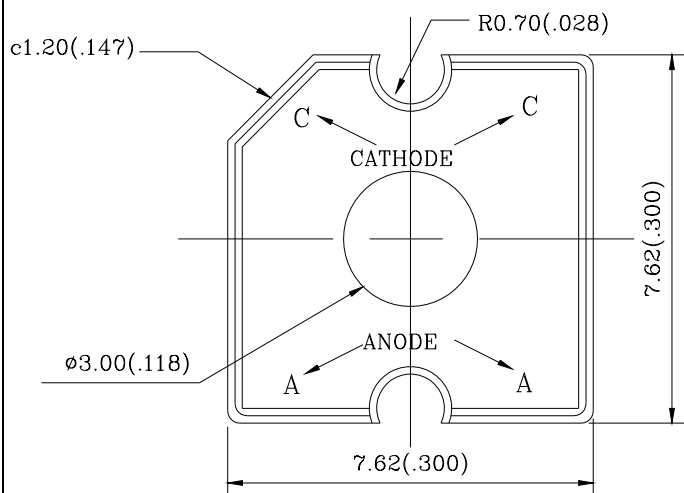
HIGH POWER LED LAMP

L-9452UBC

PACKAGE DIMENSIONS

Note:

- 1.All Dimensions are in millimeters.
- 2.Tolerance is $\pm 0.25\text{mm}$ (0.010 ") Unless otherwise specified.
- 3.Protruded resin under flange is 1.5mm(0.059 ") max.
- 4.Lead spacing is measured where the leads emerge from the package.
- 5.Specification are subject to change without notice
- 6.hilight <-400V the led can withstand the max static level when assembling or operation.





HIGH POWER LED LAMP

L-9452UBC

FEATURES

- * HIGH POWER LED LAMP
- * HIGH FLUX OUTPUT
- * DESIGNED FOR HIGH CURRENT OPERATION
- * LOW THERMAL RESISTANCE
- * LOW PROFILE
- * RELIABLE
- * PACKAGED IN TUBES FOR USE WITH AUTOMATIC INSERTION EQUIPMENT

CHIP MATERIALS

- * Dice Material : GaInN/GaN
- * Light Color : ULTRA BLUE
- * Lens Color : WATER CLEAR

ABSOLUTE MAXIMUM RATING:(Ta=25°C)

SYMBOL	DESCRIPTION	ULTRA BLUE	UNIT
PAD	Power Dissipation Per Chip	120	mW
VR	Reverse Voltage Per Chip	5	V
IF	Average Forward Current Per Chip	30	mA
-	Derating Linear From 25°C Per Chip	0.4	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	
Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C±5°C For 5 Seconds			

ELECTRO-OPTICAL CHARACTERISTICS:(Ta=25°C)

SYMBOL	DESCRIPTION	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		3.5	4.0	V
IR	Reverse Current	VR = 5V			100	μA
λD	Dominant Wavelength	IF = 20mA		470		nm
Δλ	Spectral Line Half-Width	IF = 20mA		30		nm
2θ1/2	Half Intensity Angle	IF = 20mA		70		deg
Φv	Total flux	IF = 30mA		4150		mlm

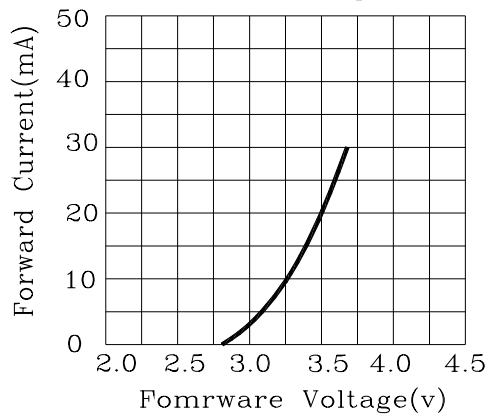


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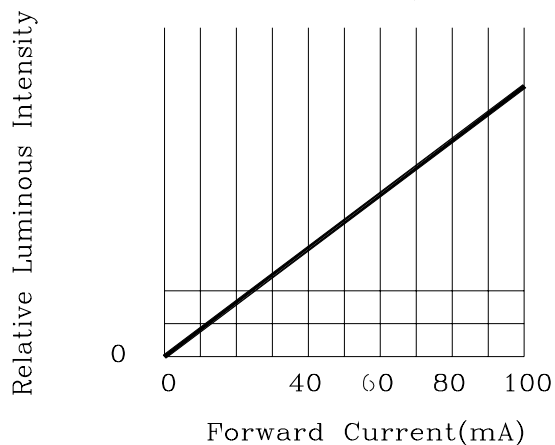
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REV:A / 0

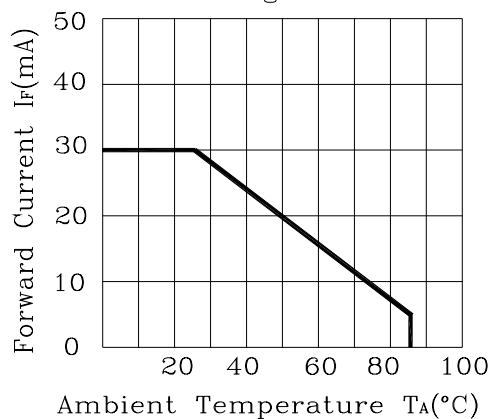
Forward Current Vs
Forward Voltage



Forward Current VS
Relative intensity



Forward Current
Derating Curve



Maximum Dc Current (mA)

